

74LVC125A

Quad buffer/line driver with 5 V tolerant input/outputs; 3-state

Rev. 7 — 11 April 2013

Product data sheet

1. General description

The 74LVC125A consists of four non-inverting buffers/line drivers with 3-state outputs ($\overline{nY}$) that are controlled by the output enable input ($\overline{nOE}$). A HIGH at $\overline{nOE}$ causes the outputs to assume a high-impedance OFF-state.

Inputs can be driven from either 3.3 V or 5 V devices. When disabled, up to 5.5 V can be applied to the outputs.

2. Features and benefits

- 5 V tolerant inputs/outputs for interfacing with 5 V logic
- Wide supply voltage range from 1.2 V to 3.6 V
- CMOS low power consumption
- Direct interface with TTL levels
- Complies with JEDEC standard:
 - ◆ JESD8-7A (1.65 V to 1.95 V)
 - ◆ JESD8-5A (2.3 V to 2.7 V)
 - ◆ JESD8-C/JESD36 (2.7 V to 3.6 V)
- ESD protection:
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-B exceeds 200 V
 - ◆ CDM JESD22-C101E exceeds 1000 V
- Multiple package options
- Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ and $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$

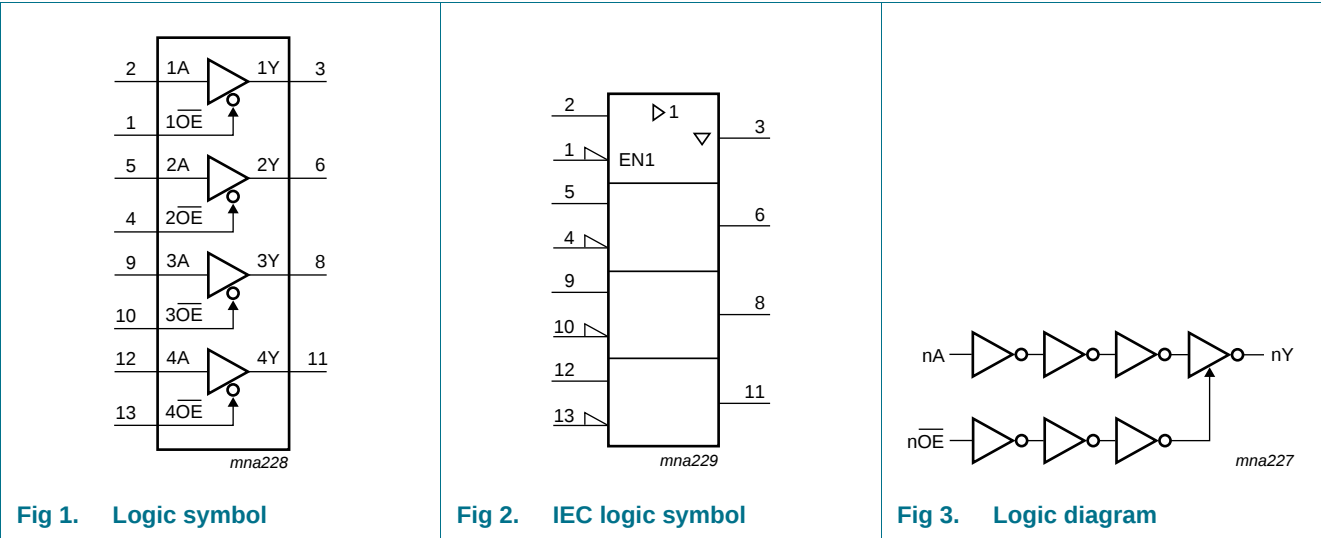


3. Ordering information

Table 1. Ordering information

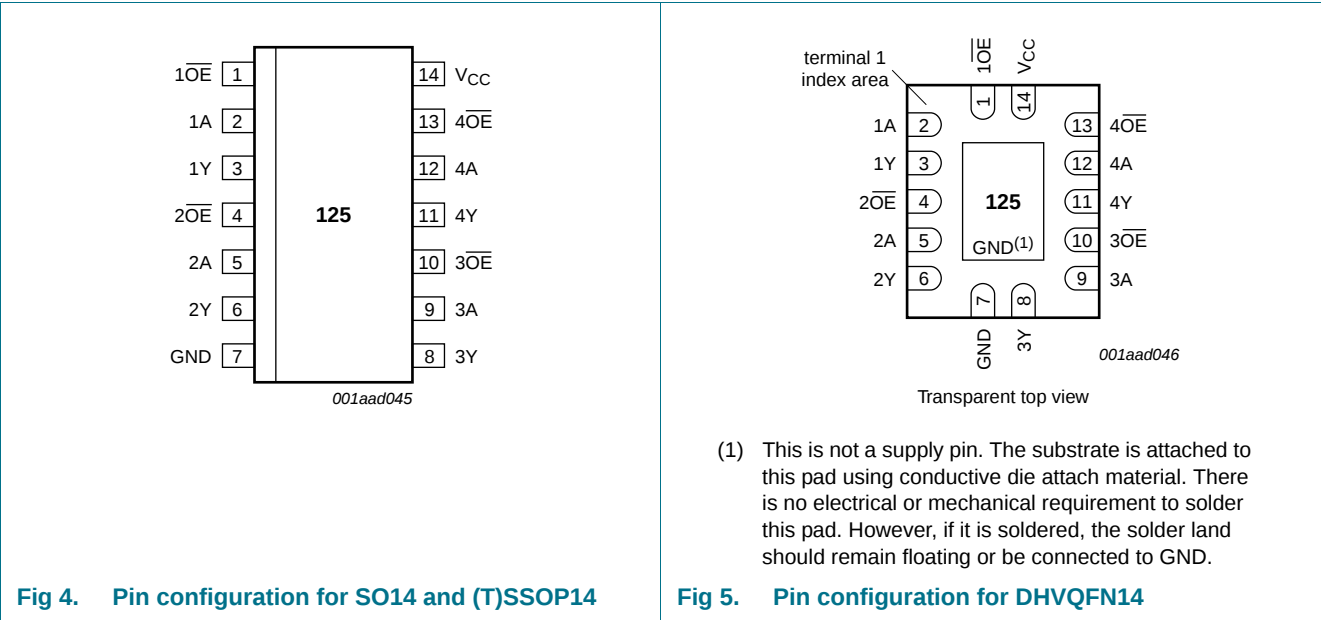
Type number	Package			Version
	Temperature range	Name	Description	
74LVC125AD	−40 °C to +125 °C	SO14	plastic small outline package; 14 leads; body width 3.9 mm; body thickness 1.47 mm	SOT108-1
74LVC125ADB	−40 °C to +125 °C	SSOP14	plastic shrink small outline package; 14 leads; body width 5.3 mm	SOT337-1
74LVC125APW	−40 °C to +125 °C	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1
74LVC125ABQ	−40 °C to +125 °C	DHVQFN14	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 × 3 × 0.85 mm	SOT762-1

4. Functional diagram



5. Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
$\overline{1OE}$, $\overline{2OE}$, $\overline{3OE}$, $\overline{4OE}$	1, 4, 10, 13	data enable input (active LOW)
1A, 2A, 3A, 4A	2, 5, 9, 12	data input
1Y, 2Y, 3Y, 4Y	3, 6, 8, 11	data output
GND	7	ground (0 V)
V _{CC}	14	supply voltage

6. Functional description

Table 3. Function selection^[1]

Inputs		Output
$\overline{nOE}$	nA	nY
L	L	L
L	H	H
H	X	Z

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+6.5	V
I_{IK}	input clamping current	$V_I < 0$ V	-50	-	mA
V_I	input voltage		[1] -0.5	+6.5	V
I_{OK}	output clamping current	$V_O > V_{CC}$ or $V_O < 0$ V	-	± 50	mA
V_O	output voltage	output HIGH or LOW-state	[2] -0.5	$V_{CC} + 0.5$	V
		output 3-state	[2] -0.5	+6.5	V
I_O	output current	$V_O = 0$ V to V_{CC}	-	± 50	mA
I_{CC}	supply current		-	100	mA
I_{GND}	ground current		-100	-	mA
P_{tot}	total power dissipation	$T_{amb} = -40$ °C to +125 °C	[3] -	500	mW
T_{stg}	storage temperature		-65	+150	°C

[1] The minimum input voltage ratings may be exceeded if the input current ratings are observed.

[2] The output voltage ratings may be exceeded if the output current ratings are observed.

[3] For SO14 packages: above 70 °C derate linearly with 8 mW/K.

For (T)SSOP14 packages: above 60 °C derate linearly with 5.5 mW/K.

For DHVQFN14 packages: above 60 °C derate linearly with 4.5 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage		1.65	-	3.6	V
		functional	1.2	-	-	V
V_I	input voltage		0	-	5.5	V
V_O	output voltage	output HIGH or LOW state	0	-	V_{CC}	V
		output 3-state	0	-	5.5	V
T_{amb}	ambient temperature		-40	-	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 2.3$ V to 2.7 V	0	-	20	ns/V
		$V_{CC} = 2.7$ V to 3.6 V	0	-	10	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
V _{IH}	HIGH-level input voltage	V _{CC} = 1.2 V	1.08	-	-	1.08	-	V
		V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}	-	-	0.65 × V _{CC}	-	V
		V _{CC} = 2.3 V to 2.7 V	1.7	-	-	1.7	-	V
		V _{CC} = 2.7 V to 3.6 V	2.0	-	-	2.0	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 1.2 V	-	-	0.12	-	0.12	V
		V _{CC} = 1.65 V to 1.95 V	-	-	0.35 × V _{CC}	-	0.35 × V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V	-	-	0.7	-	0.7	V
		V _{CC} = 2.7 V to 3.6 V	-	-	0.8	-	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}						
		I _O = –100 µA; V _{CC} = 1.65 V to 3.6 V	V _{CC} – 0.2	-	-	V _{CC} – 0.3	-	V
		I _O = –4 mA; V _{CC} = 1.65 V	1.2	-	-	1.05	-	V
		I _O = –8 mA; V _{CC} = 2.3 V	1.8	-	-	1.65	-	V
		I _O = –12 mA; V _{CC} = 2.7 V	2.2	-	-	2.05	-	V
		I _O = –18 mA; V _{CC} = 3.0 V	2.4	-	-	2.25	-	V
		I _O = –24 mA; V _{CC} = 3.0 V	2.2	-	-	2.0	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}						
		I _O = 100 µA; V _{CC} = 1.65 V to 3.6 V	-	-	0.2	-	0.3	V
		I _O = 4 mA; V _{CC} = 1.65 V	-	-	0.45	-	0.65	V
		I _O = 8 mA; V _{CC} = 2.3 V	-	-	0.6	-	0.8	V
		I _O = 12 mA; V _{CC} = 2.7 V	-	-	0.4	-	0.6	V
		I _O = 24 mA; V _{CC} = 3.0 V	-	-	0.55	-	0.8	V
I _I	input leakage current	V _{CC} = 3.6 V; V _I = 5.5 V or GND	-	±0.1	±5	-	±20	µA
I _{OZ}	OFF-state output current	V _I = V _{IH} or V _{IL} ; V _{CC} = 3.6 V; V _O = 5.5 V or GND	-	±0.1	±5	-	±20	µA
I _{OFF}	power-off leakage current	V _{CC} = 0.0 V; V _I or V _O = 5.5 V	-	±0.1	±10	-	±20	µA
I _{CC}	supply current	V _{CC} = 3.6 V; V _I = V _{CC} or GND; I _O = 0 A	-	0.1	10	-	40	µA
ΔI _{CC}	additional supply current	per input pin; V _I = V _{CC} – 0.6 V; I _O = 0 A; V _{CC} = 2.7 V to 3.6 V	-	5	500	-	5000	µA
C _I	input capacitance	V _{CC} = 0 V to 3.6 V; V _I = GND to V _{CC}	-	4.0	-	-	-	pF

[1] All typical values are measured at V_{CC} = 3.3 V (unless stated otherwise) and T_{amb} = 25 °C.

10. Dynamic characteristics

Table 7. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V). For test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
t_{pd}	propagation delay	nA to nY; see Figure 6 ^[2]						
		$V_{CC} = 1.2\text{ V}$	-	12.0	-	-	-	ns
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	1.5	5.4	11.0	1.5	12.8	ns
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	1.0	2.9	5.7	1.0	6.7	ns
		$V_{CC} = 2.7\text{ V}$	1.5	2.8	5.5	1.5	7.0	ns
t_{en}	enable time	$\overline{nOE}$ to nY; see Figure 7 ^[2]						
		$V_{CC} = 1.2\text{ V}$	-	16.0	-	-	-	ns
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	1.0	5.0	12.2	1.0	14.2	ns
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	0.5	2.9	6.8	0.5	7.9	ns
		$V_{CC} = 2.7\text{ V}$	1.5	3.1	6.6	1.5	8.5	ns
t_{dis}	disable time	$\overline{nOE}$ to nY; see Figure 7 ^[2]						
		$V_{CC} = 1.2\text{ V}$	-	7.0	-	-	-	ns
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	2.2	4.6	7.5	2.2	8.7	ns
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	0.5	2.6	4.2	0.5	5.0	ns
		$V_{CC} = 2.7\text{ V}$	1.5	3.1	5.0	1.5	6.5	ns
$t_{sk(o)}$	output skew time	$V_{CC} = 3.0\text{ V to }3.6\text{ V}$ ^[3]	-	-	1.0	-	1.5	ns
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	-	6.0	-	-	-	pF
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	-	9.4	-	-	-	pF
		$V_{CC} = 3.0\text{ V to }3.6\text{ V}$	-	12.4	-	-	-	pF
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	-	6.0	-	-	-	pF
C_{PD}	power dissipation capacitance	per buffer; $V_I = \text{GND to }V_{CC}$ ^[4]						
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	-	6.0	-	-	-	pF
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	-	9.4	-	-	-	pF
		$V_{CC} = 3.0\text{ V to }3.6\text{ V}$	-	12.4	-	-	-	pF

[1] Typical values are measured at $T_{amb} = 25\text{ °C}$ and $V_{CC} = 1.2\text{ V}, 1.8\text{ V}, 2.5\text{ V}, 2.7\text{ V}$, and 3.3 V respectively.

[2] t_{pd} is the same as t_{PLH} and t_{PHL} .

t_{en} is the same as t_{PZL} and t_{PZH} .

t_{dis} is the same as t_{PLZ} and t_{PHZ} .

[3] Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.

[4] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:

f_i = input frequency in MHz; f_o = output frequency in MHz

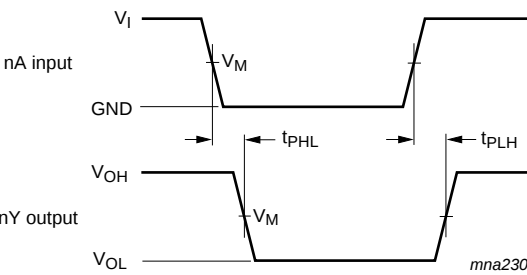
C_L = output load capacitance in pF

V_{CC} = supply voltage in Volts

N = number of inputs switching

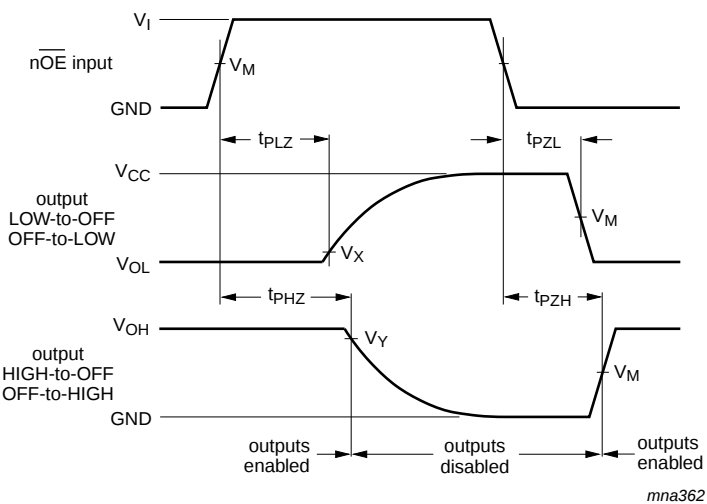
$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

11. AC waveforms



Measurement points are given in [Table 8](#).
 V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 6. The input nA to output nY propagation delays

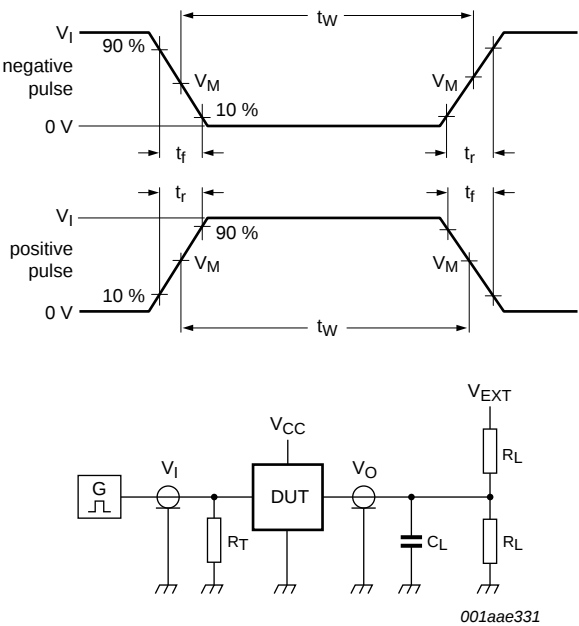


Measurement points are given in [Table 8](#).
 V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 7. 3-state enable and disable times

Table 8. Measurement points

Supply voltage	Input		Output
V_{CC}	V_I	V_M	V_M
1.2 V	V_{CC}	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
1.65 V to 1.95 V	V_{CC}	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
2.3 V to 2.7 V	V_{CC}	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
2.7 V	2.7 V	1.5 V	1.5 V
3.0 V to 3.6 V	2.7 V	1.5 V	1.5 V



Test data is given in [Table 9](#).
Definitions for test circuit:
 R_L = Load resistance.
 C_L = Load capacitance including jig and probe capacitance.
 R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.
 V_{EXT} = External voltage for measuring switching times.

Fig 8. Test circuit for measuring switching times

Table 9. Test data

Supply voltage	Input		Load		V _{EXT}		
	V _I	t _r , t _f	C _L	R _L	t _{PLH} , t _{PHL}	t _{PLZ} , t _{PZL}	t _{PHZ} , t _{PZH}
1.2 V	V _{CC}	≤ 2 ns	30 pF	1 kΩ	open	2 × V _{CC}	GND
1.65 V to 1.95 V	V _{CC}	≤ 2 ns	30 pF	1 kΩ	open	2 × V _{CC}	GND
2.3 V to 2.7 V	V _{CC}	≤ 2 ns	30 pF	500 Ω	open	2 × V _{CC}	GND
2.7 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open	2 × V _{CC}	GND
3.0 V to 3.6 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open	2 × V _{CC}	GND

12. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm SOT108-1

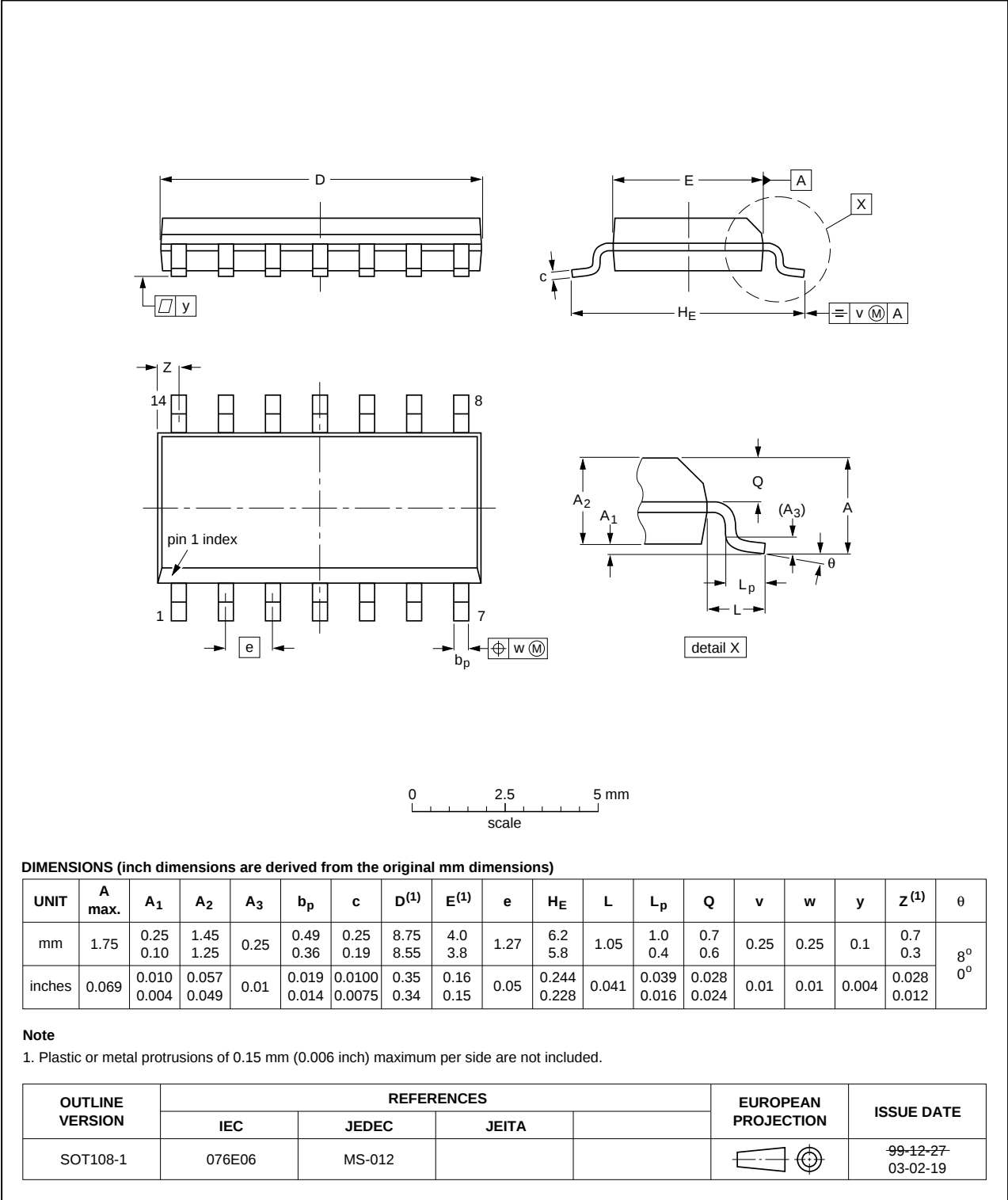


Fig 9. Package outline SOT108-1 (SO14)

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1

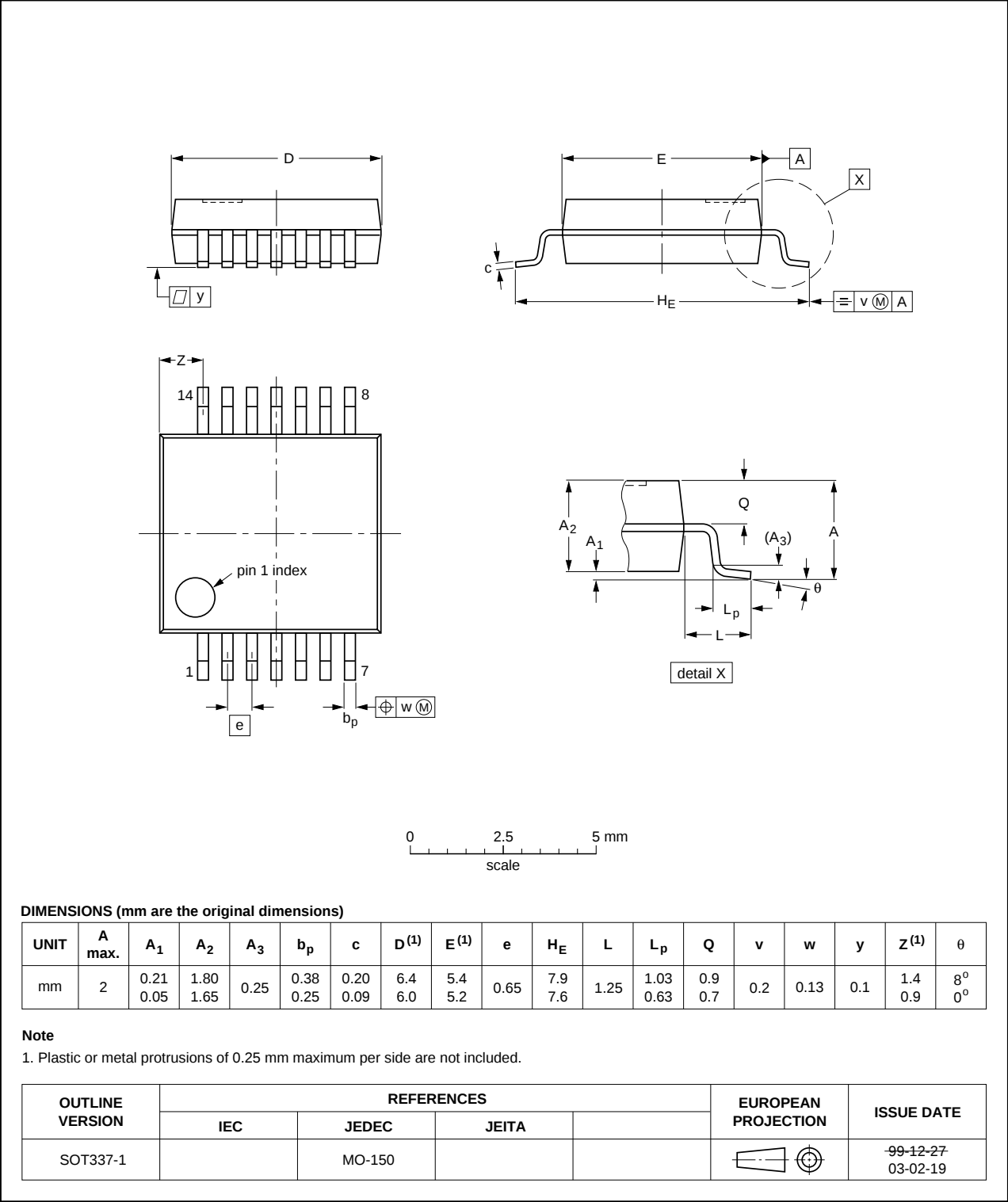


Fig 10. Package outline SOT337-1 (SSOP14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

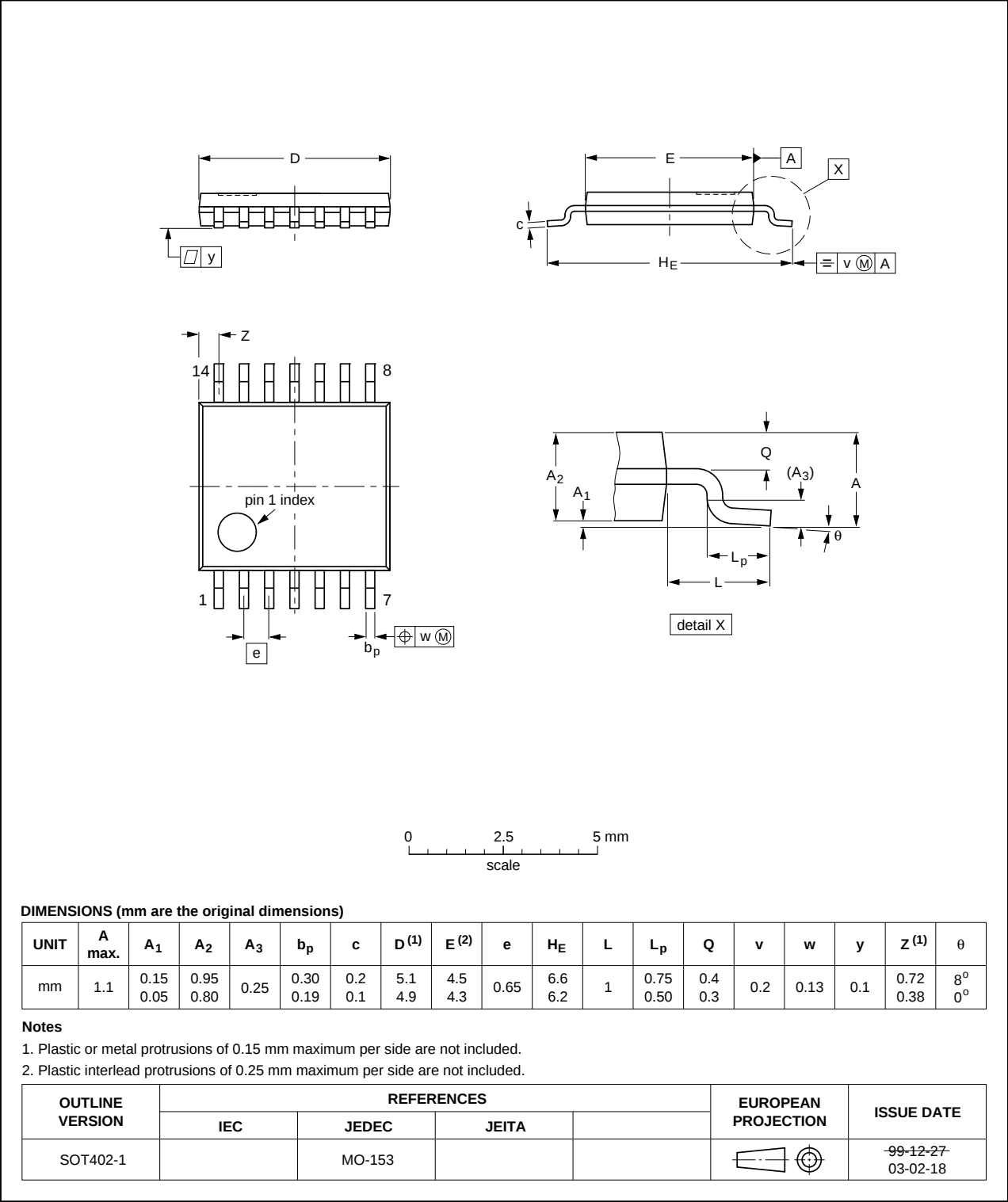


Fig 11. Package outline SOT402-1 (TSSOP14)

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads;
14 terminals; body 2.5 x 3 x 0.85 mm

SOT762-1

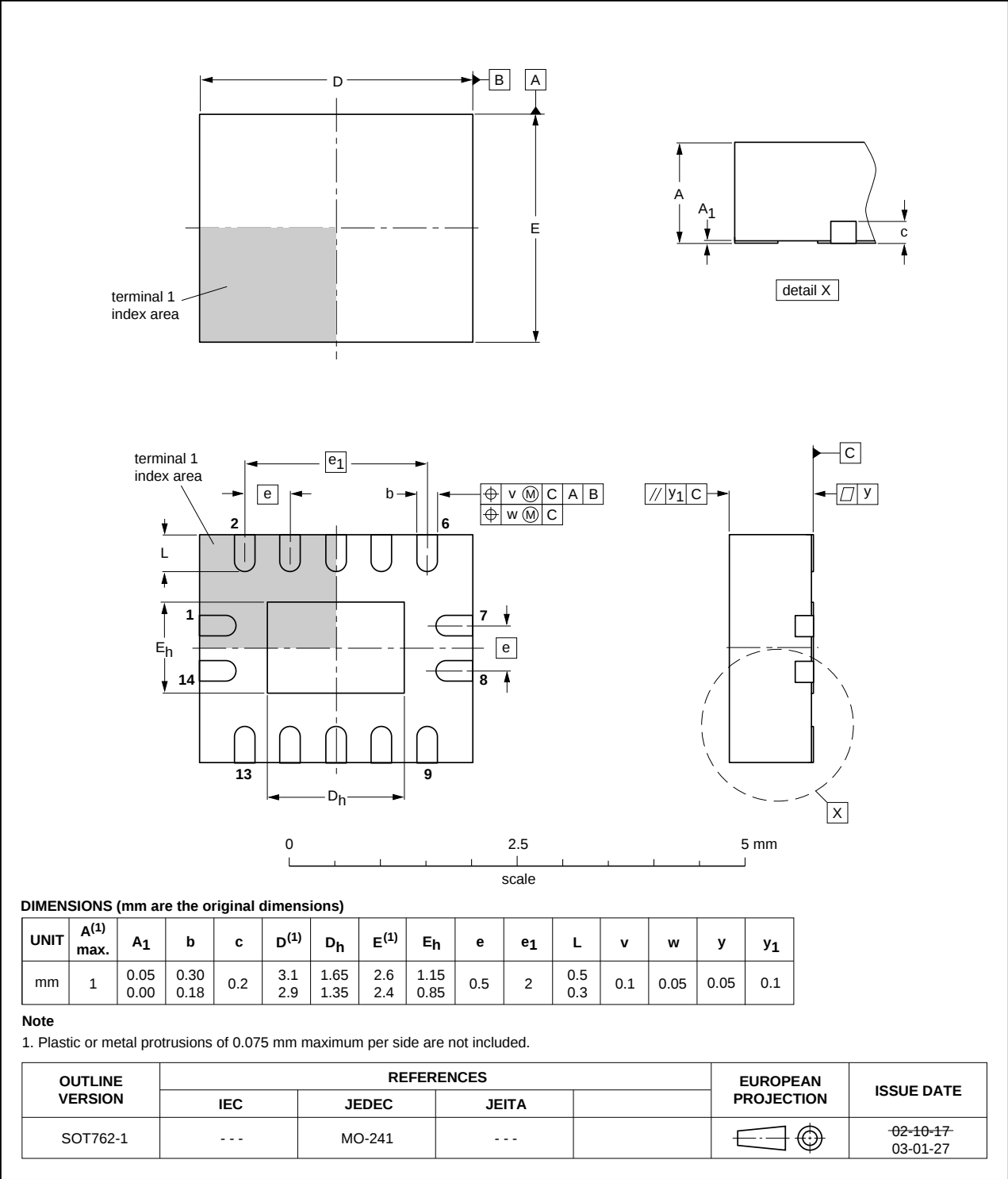


Fig 12. Package outline SOT762-1 (DHVQFN14)

13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
MM	Machine Model
HBM	Human Body Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC125A v.7	20130411	Product data sheet	-	74LVC125A v.6
Modifications:	• Features list corrected (errata)			
74LVC125A v.6	20130305	Product data sheet	-	74LVC125A v.5
74LVC125A v.5	20120208	Product data sheet	-	74LVC125A v.4
74LVC125A v.4	20030507	Product specification	-	74LVC125A v.3
74LVC125A v.3	20020308	Product specification	-	74LVC125A v.2
74LVC125A v.2	19980428	Product specification	-	74LVC125A v.1
74LVC125A v.1	19970801	Product specification	-	-

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15.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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